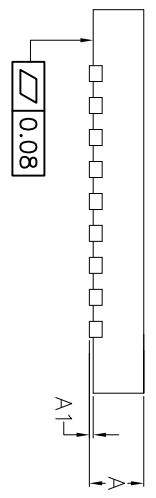
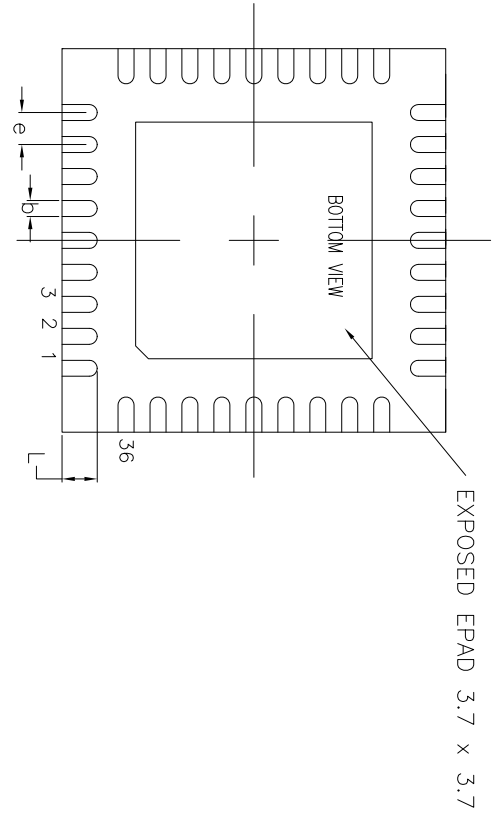
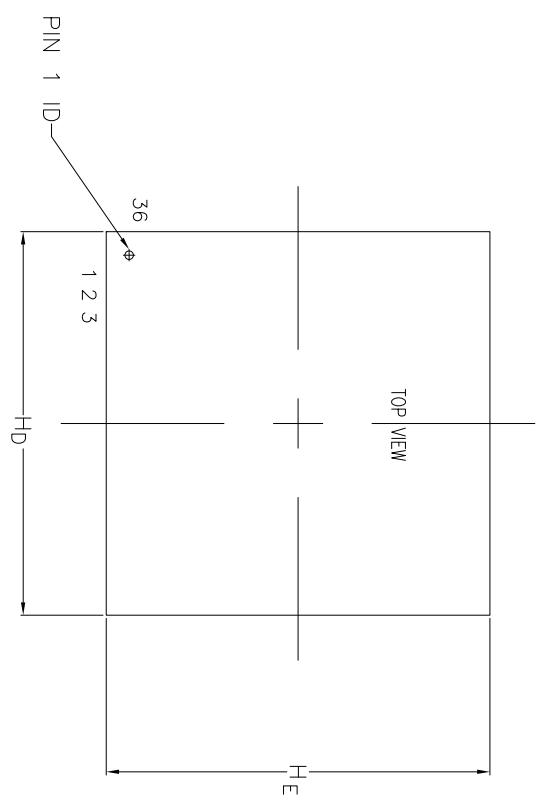


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/23/16	JHUJA

BASED ON JEDEC MO-220
 1. DIMENSIONS (IN MILLIMETERS)



- 2. WEIGHT <0.1 g
- 3. PACKAGE BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu-ALLOY
- 5. LEAD FINISH SOLDER PLATING

DIMENSIONS	min	max
A	0.8	0.9
A1	0	0.05
b	0.2	0.3
e	0.5	nom
Hd	5.9	6.1
HE	5.9	6.1
L	0.45	0.65

TOLERANCES UNLESS SPECIFIED			
DECIMAL	ANGULAR	6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727-6116 FAX: (408) 492-8674	
APPROVALS	DATE	TITLE NLG36 PACKAGE OUTLINE 6.0 x 6.0 mm BODY , EPAD 3.7 x 3.7 0.50 mm PITCH QFN	
DRAWN	DATE	SIZE	DRAWING No.
CHECKED	12/23/16	C	PSC-4648-01
DO NOT SCALE DRAWING		SHEET	1 OF 1